ZARLINK SEMICONDUCTOR

VoiceEdge

Le79231

Intelligent Subscriber Line Interface Circuit

VE790 Series

A Legerity Voice Solution

APPLICATIONS

- **Enables a cost effective voice solution for long or short loop applications providing POTS and integrated test capabilities**
  - CO
  - DLC
  - PBX/KTS
  - Pair Gain

FEATURES

- **Monitor of two-wire interface voltages and currents supports**
  - Voice transmission
  - Programmable DC feed characteristics
    - Independent of battery
    - Current limited
  - Selectable off-hook and ground-key thresholds
  - Subscriber line diagnostics
    - Leakage resistance
    - Loop resistance
    - Line capacitance
    - Bell capacitance
    - Foreign voltage sensing
  - Power cross and fault detection
- **Ring relay driver for external ringing**
- **+5 V and battery supplies**
- **Dual battery operation for system power saving**
  - Automatic battery switching
  - Intelligent thermal management
- **Compatible with inexpensive protection networks**
  - Accommodates low tolerance fuse resistors or PTC thermistors
- **Metering capable**
  - 12 kHz and 16 kHz
  - Smooth polarity reversal
- **Tip-open state supports ground start signaling**
- **Integrated test load switches/relay drivers**
- **Space Saving Package Options (8 x 8 QFN)**

ORDERING INFORMATION

A VE790 series ISLAC™ device must be used with this part.

Device	Package
Le79231JC	32-pin PLCC
Le79231DJC	32-pin PLCC (Green package)[1]
Le79231QC[2]	32-pin QFN
Le79231FQC[2]	32-pin QFN (Green package)[1]

1. Green package meets RoHS Directive 2002/95/EC of the European Council to minimize the environmental impact of electrical equipment.

2. Due to size constraints, QFN devices are marked by omitting the "Le" prefix. For example, Le79231QC is marked 79231QC.

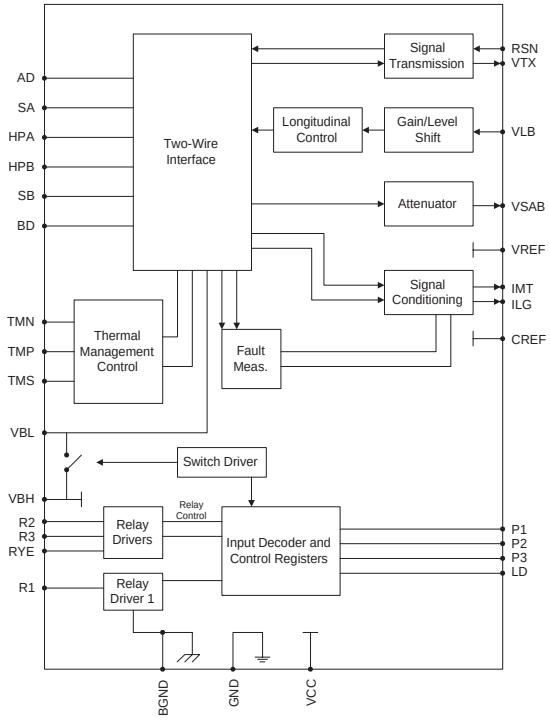
DESCRIPTION

The Le79231 ISLIC device, in combination with a VE790 series ISLAC™ device, implements the telephone line interface function. This enables the design of a low-cost, high performance, fully software programmable line interface for multiple country applications worldwide. All AC, DC, and signaling parameters are fully programmable via microprocessor or GCI interfaces on the VE790 series ISLAC devices. Additionally, the Le79231 ISLIC device has integrated self-test and line-test capabilities to resolve faults to the line or line circuit. The integrated test capability is crucial for remote applications where dedicated test hardware is not cost effective.

RELATED LITERATURE

- **080250 Le79Q2241x Quad ISLAC™ Device Data Sheet**
- **081065 Le79228 Quad ISLAC™ Device Data Sheet**
- **080262 VE790 Series Evaluation Board User's Guide**
- **080804 Le79R2xx/Le79Q224x Chip Set User's Guide**
- **080923 Le79R2xx/Le79228 Chip Set User's Guide**

BLOCK DIAGRAM



NOTE: On August 3, 2007, Zarlink Semiconductor acquired the products and technology of Legerity Holdings.

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PRODUCT DESCRIPTION

Legerity's VoiceEdge™ family voice chip sets integrate all the functions of the subscriber line. Two chip types are used to implement the line card — an Le79231 ISLIC device and a VE790 series ISLAC device. These provide the following basic functions:

1. The Le79231 ISLIC device: A high voltage, bipolar device that drives the subscriber line, maintains longitudinal balance and senses line conditions.
2. The VE790 series ISLAC devices: Low voltage CMOS ICs that provides conversion, control and DSP functions for the Le79231 ISLIC device.

A complete schematic of the line card using a VoiceEdge chip set for external ringing is shown in the *Application Circuit*, on page 19.

The Le79231 ISLIC device uses reliable, bipolar technology to provide the power necessary to drive a wide variety of subscriber lines. It can be programmed by the VE790 series ISLAC device to operate in eight different modes that control power consumption and signaling. This enables it to have full control over the subscriber loop. The Le79231 ISLIC device is designed to be used exclusively with the VE790 series ISLAC devices. The Le79231 ISLIC device requires only +5 V power and the battery supplies for its operation.

The Le79231 ISLIC device implements a linear loop-current feeding method with the enhancement of intelligent thermal management. This limits the amount of power dissipated on the Le79231 ISLIC device by dissipating power in external resistors in a controlled manner.

Each VE790 series ISLAC device contains high-performance circuits that provide A/D and D/A conversion for the voice (codec), DC-feed and supervision signals. The VE790 series ISLAC devices contain a DSP core that handles signaling, DC-feed, supervision and line diagnostics for all channels.

The DSP core selectively interfaces with three types of backplanes:

- Standard PCM/MPI
- Standard GCI
- Modified GCI with a single analog line per GCI channel

The 790 series voice chip set provides a complete software configurable solution to the BORSCHT functions as well as complete programmable control over subscriber line DC-feed characteristics, such as current limit and feed resistance. In addition, these chip sets provide system level solutions for the loop supervisory functions and metering. In total, they provide a programmable solution that can satisfy worldwide line card requirements by software configuration.

Software programmed filter coefficients, DC-feed data and supervision data are easily calculated with the WinSLAC™ software. This PC software is provided free of charge. It allows the designer to enter a description of system requirements. WinSLAC then computes the necessary coefficients and plots the predicted system results.

The Le79231 ISLIC device interface unit inside the VE790 series ISLAC devices processes information regarding the line voltages, loop currents and battery voltage levels. These inputs allow the VE790 series ISLAC devices to place several key Le79231 ISLIC device performance parameters under software control.

The main functions that can be observed and/or controlled through the VE790 series ISLAC devices backplane interface are:

- DC-feed characteristics
- Ground-key detection
- Off-hook detection
- Metering signal
- Longitudinal operating point
- Subscriber line voltage and currents
- Ring-trip detection
- Abrupt and smooth battery reversal
- Subscriber line matching
- Ringing
- Sophisticated line and circuit tests

To accomplish these functions, the Le79231 ISLIC device collects the following information and feeds it, in analog form, to the Le79Q224x or Le79228 codecs:

- The metallic (IMT) and longitudinal (ILG) loop currents
- The AC (VTX) and DC (VSAB) loop voltage

The outputs supplied by the VE790 series ISLAC device to the Le79231 ISLIC device are then:

- A voltage (VHL_i*) that provides control for the following high-level Le79231 ISLIC device outputs:

  - DC loop current
  - 12 or 16 kHz metering signal
- A low-level voltage proportional to the voice signal ($VOUT_i$)
- A voltage that controls longitudinal offset for test purposes (VLB_i)

The VE790 series ISLAC devices perform the codec and filter functions associated with the four-wire section of the subscriber line circuitry in a digital switch. These functions involve converting an analog voice signal into digital PCM samples and converting digital PCM samples back into an analog signal. During conversion, digital filters are used to band-limit the voice signals.

The user-programmable filters set the receive and transmit gain, perform the transhybrid balancing function, permit adjustment of the two-wire termination impedance and provide frequency attenuation adjustment (equalization) of the receive and transmit paths. Adaptive transhybrid balancing is also included. All programmable digital filter coefficients can be calculated using WinSLAC software. The PCM codes can be either 16-bit linear two's-complement or 8-bit companded A-law or µ-law.

Besides the codec functions, the 790 series chip set provides all the sensing, feedback, and clocking necessary to completely control the Le79231 ISLIC device functions with programmable parameters. System-level parameters under programmable control include active loop current limits, feed resistance, and feed mode voltages.

The VE790 series ISLAC devices supply complete mode control to the Le79231 ISLIC device using the control bus (P1-P3) and tri-level load signal (LD_i).

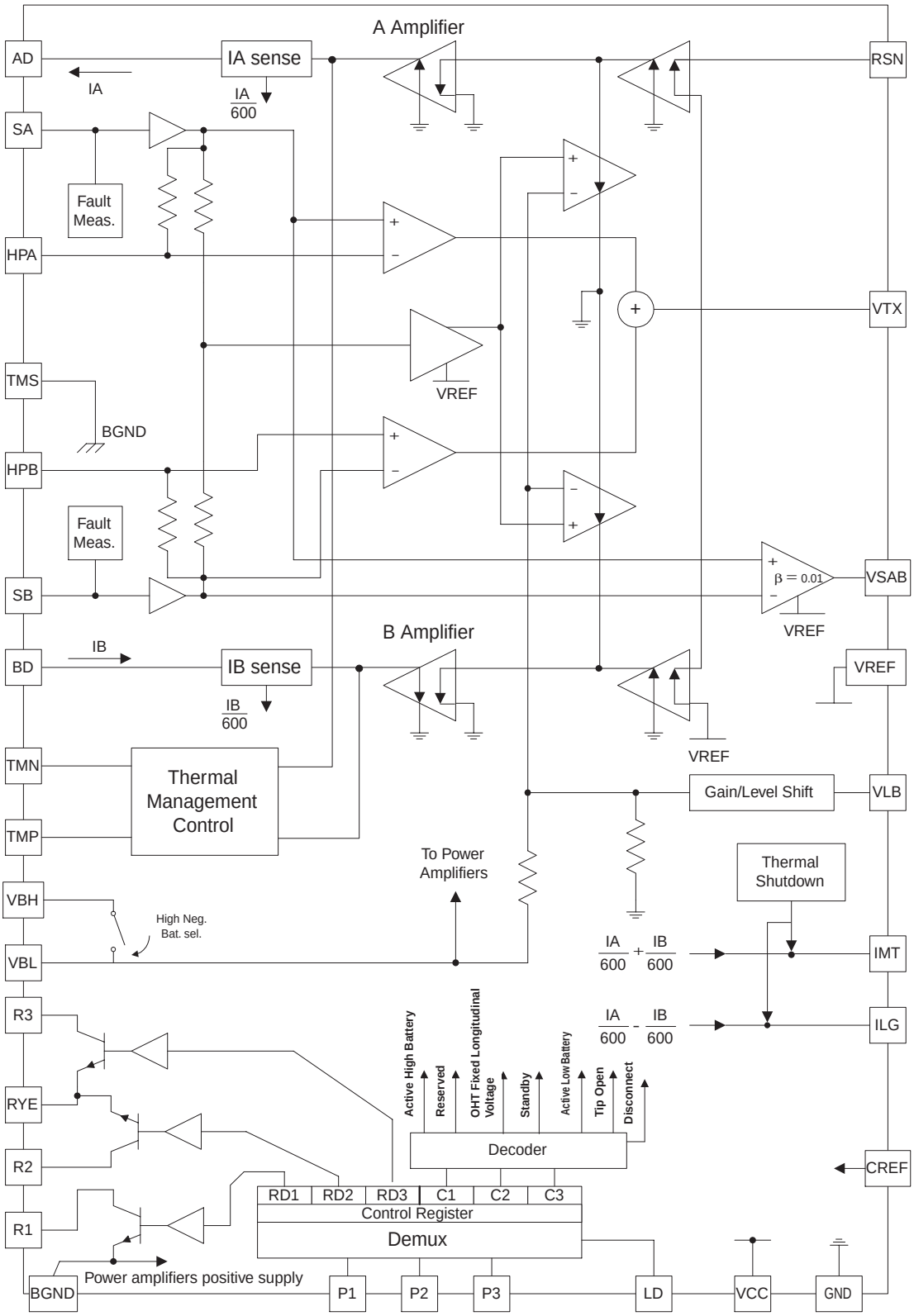
The 790 series voice chip set provides extensive loop supervision capability including off-hook, ring-trip and ground-key detection. Detection thresholds for these functions are programmable. A programmable debounce timer is available that eliminates false detection due to contact bounce.

For subscriber line diagnostics, AC and DC line conditions can be monitored using built-in test tools. Measured parameters can be compared to programmed threshold levels to set a pass/fail bit. The user can choose to send the measurement data directly to a higher level processor by way of the PCM voice channel. Both longitudinal and metallic resistance and capacitance can be measured, which allows leakage resistance, line capacitance, and telephones to be identified.

Note:

i = channel number

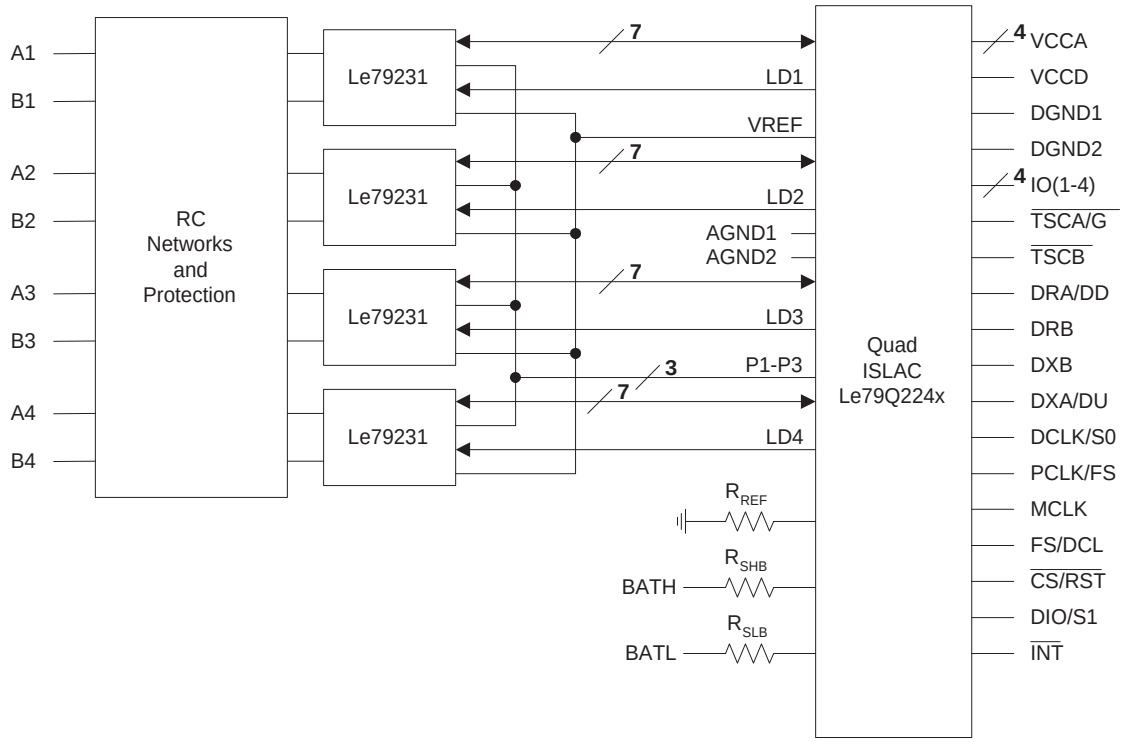
LE79231 ISLIC DEVICE INTERNAL BLOCK DIAGRAM



FEATURES OF THE VE790 SERIES CHIP SET

- Performs all battery feed, overvoltage, ring-trip, signaling, coding, hybrid and test (BORSCHT) functions
- Two chip solution supports high density, multi-channel architecture
- Single hardware design meets multiple country requirements through software programming of:
  - DC loop-feed characteristics and current-limit
  - Loop-supervision detection thresholds
    - Off-hook debounce circuit
    - Ground-key and ring-trip filters
  - Off-hook detect de-bounce interval
  - Two-wire AC impedance
  - Transhybrid balance
  - Transmit and receive gains
  - Equalization
  - Digital I/O pins
  - A-law/μ-law and linear selection
- Supports external battery-backed ringing
  - Unbalanced ringing
  - Ring relay driver
  - Ring relay operation synchronized to zero crossings of ringing voltage and current
  - Integrated ring-trip filter and software enabled manual or automatic ring-trip mode
- Supports metering generation with envelope shaping
- Smooth or abrupt polarity reversal
- Adaptive transhybrid balance
  - Continuous or adapt and freeze
- Supports both loop-start and ground-start signaling
- Exceeds LSSGR and CCITT central office requirements
- Selectable PCM or GCI interface
  - Supports most available master clock frequencies from 512 kHz to 8.192 MHz
- On-hook transmission
- Power/service denial mode
- Line-feed characteristics independent of battery voltage
- Only 5 V, 3.3 V and battery supplies needed
- Low idle-power per line
- Linear power-feed with intelligent power-management feature
- Compatible with inexpensive protection networks; Accommodates low-tolerance fuse resistors while maintaining longitudinal balance
- Monitors two-wire interface voltages and currents for subscriber line diagnostics
- Built-in voice-path test modes
- Power-cross, fault, and foreign voltage detection
- Integrated line-test features
  - Leakage
  - Line and ringer capacitance
  - Loop resistance
- Integrated self-test features
  - Echo gain, distortion, and noise
- Guaranteed performance over commercial and industrial temperature ranges.
- Up to three relay drivers per Le79231 ISLIC device
  - Configurable as test load switches

CHIP SET BLOCK DIAGRAM - FOUR CHANNEL LINE CARD EXAMPLE



CONNECTION DIAGRAMS

Figure 1. Le79231JC

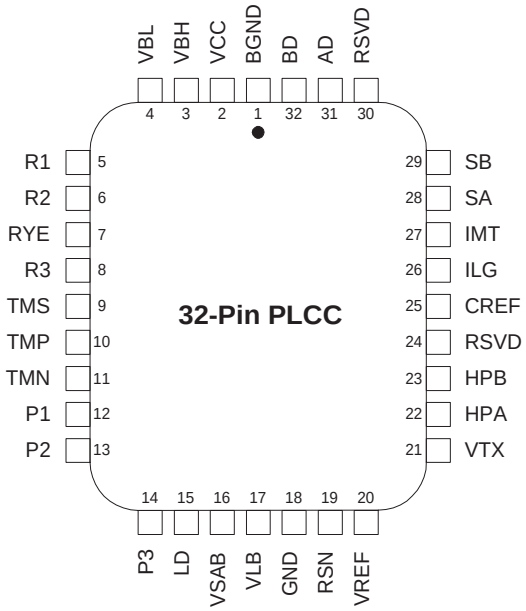
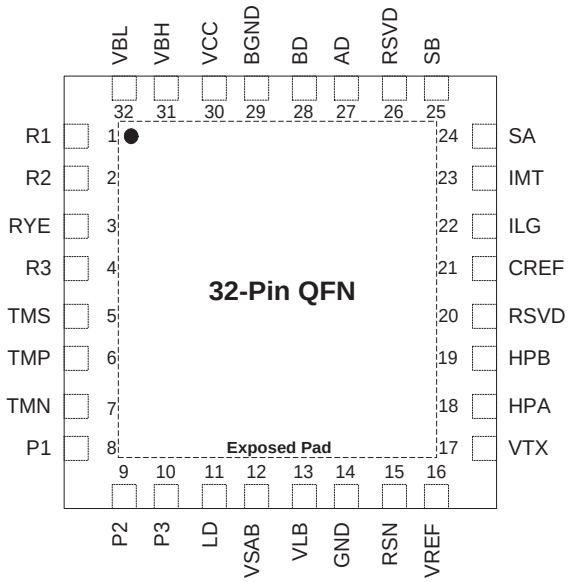


Figure 2. Le79231QC



Notes:

1. *Pin 1 is marked for orientation.*
2. *RSVD = Reserved. Do not connect to this pin.*
3. *The thermally enhanced QFN package features an exposed pad on the underside which must be electrically tied to VBH.*

PIN DESCRIPTIONS

Pin Name	Type	Description
AD, BD	Output	Provide the currents to the A and B leads of the subscriber loop.
BGND	Ground	Ground return for high and low battery supplies.
CREF	+3.3 VDC	VCCD reference. It is the digital high logic supply rail, used by the Le79231 to codec interface.
GND	Ground	Analog and digital ground return for VCC.
HPA, HPB	Output	These pins connect to CHP, the external high-pass filter capacitor that separates the DC loop-voltage from the voice transmission path.
ILG	Output	ILG is proportional to the common-mode line current (IAD–IBD), except in disconnect mode, where ILG is proportional to the current into grounded SB.
IMT	Output	IMT is proportional to the differential line current (IAD + IBD), except in disconnect mode, where IMT is proportional to the current into grounded SA. The Le79231 ISLIC device indicates thermal overload by pulling IMT to CREF.
LD	Input	The LD pin controls the input latch and responds to a 3-level input. When the LD pin is a logic 1 (C_{REF} – 1), the logic levels on P1–P3 latch into the Le79231 ISLIC device control register bits that operate the mode-decoder. When the LD pin is a logic 0 (< 0.6), the logic levels on P1–P3 latch into the Le79231 ISLIC device control register bits that control the relay drivers (RD1–RD3). When the LD pin level is at ~V_{REF} ± 0.3 V, the control register contents are locked.
P1–P3	Input	Inputs to the latch for the operating-mode decoder and the relay-drivers.
R1	Output	Collector connection for ring relay driver. Emitter internally connected to BGND.
R2	Output	Collector connection for relay 2 driver. Emitter internally connected to RYE
R3	Output	Collector connection for relay 3 driver. Emitter internally connected to RYE.
RSN	Input	The metallic current between AD and BD is equal to 500 times the current into this pin. Networks that program receive gain and two-wire impedance connect to this node. This input is at a virtual potential of VREF.
RSVD	Reserved	These pins are used during Legerity testing. In the application, these pins must be left floating.
RYE	Output	Emitter connection for R2 and R3. Normally connected to relay ground.
SA, SB	Input	Sense the voltages on the line side of the fuse resistors at the A and B leads. External sense resistors, RSA and RSB, protect these pins from lightning or power-cross.
TMP, TMN, TMS	Output	External resistors connected from TMP to TMS and TMN to VBL to offload excess power from the Le79231 ISLIC device.
VBH	Battery (Power)	Connection to high-battery supply used for ringing and long loops. Connects to the substrate. When only a single battery is available, it connects to both VBH and VBL.
VBL	Battery (Power)	Connection to low-battery supply used for short loops. When only a single battery is available, this pin can be connected to VBH.
VCC	Power	+5 V Power Supply supply for low voltage analog and digital circuits in the Le79231 ISLIC device.
VLB	Input	Sets the DC longitudinal voltage of the Le79231 ISLIC device. It is the reference for the longitudinal control loop. When the VLB pin is greater than V_{REF}, the Le79231 ISLIC device sets the longitudinal voltage to a voltage approximately half-way between the positive and negative power supply battery rails. When the VLB pin is driven to levels between 0 V and V_{REF}, the longitudinal voltage decreases linearly with the voltage on the VLB pin.
VREF	Input	The VE790 series ISLAC device provides this voltage which is used by the Le79231 ISLIC device for internal reference purposes. All analog input and output signals interfacing to the VE790 series ISLAC device are referenced to this pin.
VSAB	Output	Scaled-down version of the voltage between the sense points SA and SB on this pin.
VTX	Output	The voltage between this pin and V_{REF} is a scaled down version of the AC component of the voltage sensed between the SA and SB pins. One end of the two-wire input impedance programming network connects to VTX. The voltage at VTX swings positive and negative with respect to V_{REF}.
Exposed Pad	Battery	This must be electrically tied to VBH.

ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Stresses above those listed under *Absolute Maximum Ratings* can cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods can affect device reliability.

Storage temperature	–55° to +150° C
Ambient temperature, under bias	–40° to +85° C
Humidity	5% to 95%
VCC with respect to GND	–0.4 to +7 V
VBH, VBL with respect to GND (see note 2)	+0.4 to –70 V
BGND with respect to GND	–3 to +3 V
Voltage on relay outputs	+7 V
AD or BD to BGND: Continuous 10 ms (F = 0.1 Hz) 1 µs (F = 0.1 Hz) 250 ns (F = 0.1 Hz)	 VBH – 1 to BGND + 1 VBH – 5 to BGND + 5 VBH – 10 to BGND + 10 VBH – 15 to BGND + 15
Current into SA or SB: 10 µs rise to Ipeak 1000 µs fall to 0.5 Ipeak; 2000 µs fall to I =0	Ipeak = ±5 mA
Current into SA or SB: 2 µs rise to Ipeak 10 µs fall to 0.5 Ipeak; 20 µs fall to I = 0	Ipeak = ±12.5 mA
SA SB continuous	5 mA
Current through AD or BD	± 150 mA
P1, P2, P3, LD to GND	–0.4 to VCC + 0.4 V
Maximum power dissipation (see note 1) T_A = 70° C In 32-pin PLCC package In 32-pin QFN package T_A = 85° C In 32-pin PLCC package In 32-pin QFN package	 1.67 W 3.00 W 1.33 W 2.40 W
ESD Immunity (Human Body Model)	JESD22 Class 1C compliant

Notes:

1. *Thermal limiting circuitry on chip will shut down the circuit at a junction temperature of about 165° C. Operation above 145° C junction temperature may degrade device reliability.*

   The thermal performance of a thermally enhanced package is assured through optimized printed circuit board layout. Specified performance requires that the exposed thermal pad be soldered to an equally sized exposed copper surface, which, in turn, conducts heat through multiple vias to a large internal copper plane.

2. *Rise time of VBH (dv/dt) must be limited to less than 27 v/µs.*

Thermal Resistance

The junction to air thermal resistance of the Le79231 ISLIC device in a 32-pin PLCC package is 45° C/W and in a 32-pin QFN package is 25° C/W (measured under free air convection conditions and without external heat sinking).

Package Assembly

The standard (non-green) package devices are assembled with industry-standard mold compounds, and the leads possess a tin/lead (Sn/Pb) plating. These packages are compatible with conventional SnPb eutectic solder board assembly processes. The peak soldering temperature should not exceed 225°C during printed circuit board assembly.

The green package devices are assembled with enhanced, environmental compatible lead-free, halogen-free, and antimony-free materials. The leads possess a matte-tin plating which is compatible with conventional board assembly processes or newer lead-free board assembly processes. The peak soldering temperature should not exceed 245°C during printed circuit board assembly.

Refer to IPC/JEDEC J-Std-020B Table 5-2 for the recommended solder reflow temperature profile.

Operating Ranges

Legerity guarantees the performance of this device over commercial (0 to 70º C) and industrial (-40 to 85ºC) temperature ranges by conducting electrical characterization over each range and by conducting a production test with single insertion coupled to periodic sampling. These characterization and test procedures comply with section 4.6.2 of Bellcore GR-357-CORE Component Reliability Assurance Requirements for Telecommunications Equipment.

Environmental Ranges

Ambient Temperature	0 to 70° C Commercial
	–40 to +85 ° C extended temperature
Ambient Relative Humidity	15 to 85%

Electrical Ranges

VCC	5 V ± 5%
VBL	–15 V to VBH
VBH	–42.5 to –70V
BGND with respect to GND	–100 to +100 mV
Load resistance on VTX to V_{REF}	20 kΩ minimum
Load resistance on VSAB to V_{REF}	20 kΩ minimum

SPECIFICATIONS

Power Dissipation

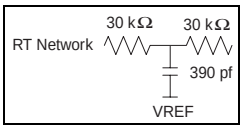
Loop resistance = 0 to ∞ unless otherwise noted (not including fuse resistors), 2 x 50 Ω fuse resistors, BATL = –36 V, BATH = –90 V, VCC = +5 V. For power dissipation measurements, DC-feed conditions are as follows:

- ILA (Active mode current limit) = 25 mA (IRSN = 50 µA)
- RFD (Feed resistance) = 500 Ω
- VAS (Anti-sat activate voltage) = 10 V
- VAPP (Apparent Battery Voltage) = 48 V
- RMGLi = RMGPi (Thermal management resistors) = 1 kΩ

Description	Test Conditions	Min	Typ	Max	Unit
Power Dissipation Normal Polarity	On-Hook Disconnect		55	70	mW
	On-Hook Standby		80	100	
	On-Hook Transmission Le79231 ISLIC device Fixed Longitudinal Voltage		175	215	
	On-Hook Active High Battery Le79231 ISLIC device		340	400	
	Off-Hook Active Low Battery Le79231 ISLIC device RL = 294 Ω TMG		700 200	800	
Power Supply Currents	On-Hook Disconnect VBH VBL VCC		0.4 0.1 3.1	0.7 3.5	mA
	On-Hook Standby VBH VBL VCC		0.75 0 3.1	1.1 3.5	
	On-Hook Transmission Fixed Longitudinal Voltage VBH VBL VCC		1.85 0 5	2.5 6	
	On-Hook Active High Battery VBH VBL VCC		3.6 0 7.3	4.5 8.0	
	Off-Hook Active Low Battery VBH RL = 294 Ω VBL VCC		0.9 26.9 7.5	2.0 10	

DC SPECIFICATIONS

Unless otherwise specified, test conditions are: VCC = 5 V, $RMGP_i$ = $RMGL_i$ = 1 kΩ, BATH = –90 V, BATL = –36 V, RRX = 150 kΩ, RL = 600 Ω, RSA = RSB = 200 kΩ, RFA = RFB = 50 Ω, CHP = 22 nF, CAD = CBD = 22 nF, IRSN = 50 mA. DC-feed conditions are normally set by the VE790 series codec. When the Le79231 ISLIC device is tested by itself, its operating conditions must be simulated as if it were connected to an ideal codec.

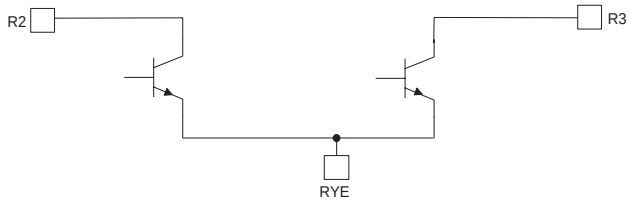


No.	Item	Condition	Min	Typ	Max	Unit	Note
1	Two-wire loop voltage (including offset)	Standby mode, open circuit, |VBH| < 55 V |VBH| > 55 V GND – VB Any Active mode (does not include OHT), RL = 600 Ω, I_{RSN} = 50 µA OHT mode, RL = 2200 Ω I_{RSN} = 20 µA	 VBH–8 48 13.88 19.8	 VBH–7 51 15 22	 VBH–6 55.5 55.5 16.13	V	2
2	Feed resistance per leg at pins AD & BD	Standby mode	130	250	375	Ω	
3	Feed current limit	Feed current Standby mode, RL = 600 Ω	18	34	45	mA	
	IMT current	Standby mode, RL = 2200 Ω	44.6	56		µA	
	ILG current	Standby mode A to VBH B to Ground	 28 28				
4	Ternary input voltage boundaries for LD pin. Mid-level input source must be V_{REF}.	Low boundary Mid boundary High boundary Input high current Input low current Mid-level current	 VREF–0.3 CREF–1	 V_{REF} 108 47 51	0.6 VREF+0.3	V V V µA µA µA	 2 2 2
5	Logic Inputs P1, P2, P3	Input high voltage Input low voltage Input high current Input low current	2.0 –20 –20	 0 0	 0.8 20 20	V V µA µA	
6	VTX output offset		–50	0	+50	mV	
7	VREF input current	VREF = 1.4 V		50		µA	2
8	CREF input current	CREF = 3.3 V	–3	0	3	µA	2
9	ß, DC Ratio of VSAB to loop voltage: $\beta = \frac{V_{SAB}}{V_{SA} - V_{SB}}$	Tj < 145° C, VSA – VSB = 22 V	0.0088	0.0097	0.0106	V/V	
10	Fault Indicator Threshold	Voltage Output on IMT	2.8	CREF - 0.3 V	CREF	V	2
11	Gain from VLB pin to A or B pin,KLG			30		V/V	
12	VLB pin input current	VLB = VREF ±1 V		0	100	µA	2
13	ILOOP/IMT	ILOOP = 10 mA	275	300	325	A/A	
14	ILONG/ILG	ILONG = 10 mA	565	605	645	A/A	
15	Input current, SA and SB pins	Active modes		1.0	3.0	µA	2
16	K1	Incremental DC current gain	462.5	500	537.5	A/A	2
17	ISA/IMT	Disconnect, ISA = 2 mA	4	6	8.75		
18	ISB/ILG	Disconnect, ISB = 2 mA	10	12	16		
19	VSAB output offset	–40° C +25° C +85° C		7.0 3.6 1.4		mV	
20	IMT output offset		-3	0	3	µA	
21	ILG output offset		-1	0	1	µA	

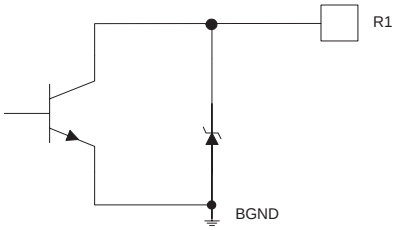
Relay Driver Specifications

Item	Condition	Min	Typ	Max	Unit	Note
On Voltage	25 mA/relay sink		0.4	0.5	V	2
	40 mA/ relay sink		0.8	1.0		
R2,R3 Off Leakage	R2,R3 = BGND RYE = VBH		0	100	µA	
Zener Break Over	Iz = 100 µA	6.6	7.9	10	V	
Zener On Voltage	Iz = 30 mA	6	11	17		

Figure 3. Relay Drivers



A. Relay Driver Configuration



B. Ring Relay

Transmission Specifications

No.	Item	Condition	Min	Typ	Max	Unit	Note
1	RSN input impedance	f = 300 to 3400 Hz		1		Ω	2
2	VTX output impedance			3			
3	Max, AC + DC loop current	Active High Battery or Active Low Battery	70			mA	2
4	Longitudinal impedance, A or B to GND	Active mode		70	135	Ω	
5	2-4 wire gain	–10 dBm, 1 kHz, 0 to 70° C T_A = –40° to 85° C	–14.13 –14.18	–13.98 –13.98	–13.83 –13.78	dB	2
6	2-4 wire gain variation with frequency	300 to 3400 Hz, relative to 1 kHz T_A=–40° to 85° C	–0.10 –0.15		+.10 +.15		2
7	2-4 wire gain tracking	+3 dBm to –55 dBm Reference: –10 dBm T_A = –40 to 85° C	–0.10 –0.15		+0.10 +0.15		2, 5
8	4-2 wire gain	–10 dBm, 1 kHz T_A= –40° to 85° C	–0.15 –0.20		+0.15 +0.20		2
9	4-2 wire gain variation with frequency	300 to 3400 Hz, relative to 1 kHz	–0.1		+0.1		
10	4-2 wire gain tracking	+3 dBm to –55 dBm Reference: –10 dBm T_A = –40 to 85° C	–0.1 –0.15		+0.1 +.15		2, 5
11	Total harmonic distortion level 2-wire 4-wire 4-wire overload level at VTX	300 Hz to 3400 Hz 0 dBm 11.2 dBm –12 dBm –0.8 dBm RLOAD = 600 Ω VAB-50 0 dBm		 ±1 -50	 –50 –40 –48 –38	 dB dB dB dB Vp dB	 2 2
12	Idle channel noise C-message Weighted Psophometric Weighted	Active modes, R_L = 600 Ω 2-wire 4-wire 2-wire 4-wire		 +9 –5 –81 –95	 +11 –79	 dBrnC dBmp —	
13	Longitudinal balance (IEEE method) Normal Polarity	L - T 200 to 1000 Hz T_A = –40° to 85° C 1000 to 3400 Hz T_A = –40° to 85° C	58 53 53 48			dB	2 2
		T - L 200 to 3400 Hz	40				
		L - T, IL = 0 50 to 3400 Hz		63			3
	Reverse Polarity	L - T 200 to 1000 Hz T_A = –40° to 85° C	50 48				
14	PSRR (VBH, VBL)	50 to 3400 Hz 3.4 to 50 kHz	25	45 40			3, 4 1, 2, 4
15	PSRR (VCC)	50 to 3400 Hz 3.4 to 50 kHz	25	45 35			3, 4 1, 2, 4
16	Longitudinal AC current per wire	F = 15 to 60 Hz Active mode	20	30		mArms	2
17	Metering distortion	Freq = 12 kHz 2.8 Vrms Freq = 16 kHz metering load = 200 Ω	40			dB	2

Current-Limit Behavior

SLIC Mode	Condition	Min	Typ	Max	Unit	Note
Disconnect	Applied fault between ground and T/R VBH applied to Tip or Ring		1 VBH/200 kΩ	100	µA A	6
Tip Open	Ring Short to GND	20	35	46	mA	
Standby	Short Tip-to-VBH Short Ring-to-GND	24 26	38 35	47 44		

Thermal Shutdown Fault Indications

Fault	Indication
No Fault	IMT operates normally (V_{REF} ±1 V)
Thermal Shutdown	KG, IMT above 2.8 V; ILG operates normally

Note:

1. *These tests are performed with the following load impedances:*
   Frequency < 12 kHz – Longitudinal impedance = 500 Ω; metallic impedance = 300 Ω
   Frequency > 12 kHz – Longitudinal impedance = 90 Ω; metallic impedance = 135 Ω
2. *Not tested or partially tested in production. This parameter is guaranteed by characterization or correlation to other tests.*
3. *This parameter is tested at 1 kHz in production. Performance at other frequencies is guaranteed by characterization.*
4. *When the Le79231 ISLIC device and VE790 series ISLAC device are in the anti-sat operating region, this parameter is degraded. The exact degradation depends on system design.*
5. *–55 dBm gain tracking level not tested in production. This parameter is guaranteed by characterization and correlation to other tests.*
6. *This spec is valid from 0 V to VBL or –50 V, whichever is lower in magnitude.*

OPERATING MODES

The Le79231 ISLIC device receives multiplexed control data on the P1, P2 and P3 pins. The LD pin then controls the loading of P1, P2, and P3 values into the proper bits in the Le79231 ISLIC device control register. When the LD pin is less than 0.3 V below V_{REF} (< (V_{REF} – 0.3 V)), P1–P3 must contain data for relay control bits RD1, RD2 and RD3. These are latched into the first three bits in the Le79231 ISLIC device control register. When the LD pin is more than 0.3 V above V_{REF}, P1–P3 must contain Le79231 ISLIC device control data C1, C2, and C3, which are latched into the last three bits of the Le79231 ISLIC device control register. Connecting the LD pin to VREF locks the contents of the Le79231 ISLIC device control register.

The operating mode of the Le79231 ISLIC device is determined by the C1, C2, and C3 bits in the control register of the Le79231 ISLIC device. Table 1 defines the Le79231 ISLIC device operating modes set by these signals.

Under normal operating conditions, the Le79231 ISLIC device does not have active relays. The Le79231 ISLIC device to VE790 series ISLAC device interface is designed to allow continuous real-time control of the relay drivers to avoid incorrect data loads to the relay bit latches of the Le79231 ISLIC device.

To perform external ringing, the VE790 series ISLAC device is set to external ringing mode (RMODE = 1), enables the ring relay, and puts the Le79231 ISLIC device in the Standby mode.

Table 1. Operating Modes

C3	C2	C1	Operating Mode	Battery Voltage Selection	Operating Mode	Connection to RMGPi & RMGLi Resistors
0	0	0	Standby (See note 1)	High Battery (BATH) and BGND	(High ohmic feed): Loop supervision active, A and B amplifiers shut down	Open
0	0	1	Tip Open (See note 1)	High Battery (BATH) and BGND	Tip Open: AD at High-Impedance, Channel A power amplifier shut down	Open
0	1	0	On-Hook Transmission, Fixed Longitudinal Voltage	High Battery (BATH) and BGND	Fixed longitudinal voltage of –28 V	
0	1	1	Disconnect	Low Battery selection at VBL	AD and BD at High-Impedance, Channel A and B power amplifiers shut down	A and B Amplifier Output

Table 1. Operating Modes(Continued)

C3	C2	C1	Operating Mode	Battery Voltage Selection	Operating Mode	Connection to RMGPi & RMGLi Resistors
1	0	0	RSVD		Active feed, normal or reverse polarity	
1	0	1	Active High Battery	High Battery (BATH) and BGND		A and B Amplifier Output
1	1	0	Active Low Battery	Low Battery (BATL) and BGND		A and B Amplifier Output
1	1	1	RSVD			

Note:

1. In these modes, the ring lead (B-lead) output has a –50 V internal clamp to battery ground (BGND).

Operating Mode Descriptions

Operating Mode	Description
Disconnect	This mode disconnects both A and B output amplifiers from the AD and BD outputs. The A and B amplifiers are shut down and the Le79231 ISLIC device selects the low battery voltage at the VBL pin. In the Disconnect state, the currents on IMT and ILG represent the voltages on the SA and SB pins, respectively. These currents are scaled to produce voltages across RMTi and RLGi of $\frac{V_{SA}}{400}$ and $\frac{V_{SB}}{400}$, respectively.
Standby	The power amplifiers are turned off. The AD output is driven by an internal 250 Ω (typical) resistor, which connects to ground. The BD output is driven by an internal 250 Ω (typical) resistor, which connects to the high battery (BATH) at the VBH pin, through a clamp circuit, which clamps to approximately –50 V with respect to BGND. For VBH values above –55 V, the open-circuit voltage, which appears at this output is ~VBH + 7 V. If VBH is below –55 V, the voltage at this output is –50 V. The battery selection for the balance of the circuitry on the chip is VBL. Line supervision remains active. Current limiting is provided on each line to limit power dissipation under short-loop conditions as specified in the “Le79231 ISLIC device Current-Limit Behavior” section. In external ringing, the standby ISLIC state is selected.
Tip Open	In this mode, the AD (Tip) lead is opened and the BD (Ring) lead is connected to a clamp, which operates from the high battery on VBH pin and clamps to approximately –50 V with respect to BGND through a resistor of approximately 250 Ω (typical). The battery selection for the balance of the circuitry on the chip is VBL.
Active High Battery	In the Active High Battery mode, battery connections are as shown in Table 1. Both output amplifiers deliver the full power level determined by the programmed DC-feed conditions. Active High Battery mode is enabled during a call in applications when a long loop can be encountered.
Active Low Battery	Both output amplifiers deliver the full power level determined by the programmed DC-feed conditions. VBL, the low negative battery, is selected in the Active Low Battery mode. This is typically used during the voice part of a call.
On-Hook Transmission (OHT), Fixed Longitudinal Voltage	In the On-Hook Transmission, Fixed Longitudinal Voltage mode, battery connections are as shown in Table 1. The longitudinal voltage is fixed at the voltage shown in Table 1 to allow compliance with safety specifications for some classes of products.

Driver Descriptions

Driver	Description
R1	A logic 1 on RD1 turns the R1 driver on and operates a relay connected between the R1 pin and VCCD. R1 drives the ring relay when external ringing is selected.
R2	A logic 1 on the RD2 signal turns the R2 driver on and routes current from the R2 pin to the RYE pin. In the option where the RYE pin is connected to ground, the R2 pin can sink current from a relay connected to VCCD. Another option is to connect the RYE pin to the BD (Ring) lead and connect a test load between R2 and the AD (Tip) lead. This technique avoids the use of a relay to connect a test load. However, it does not isolate the subscriber line from the line card. The test load must be connected to the Le79231 ISLIC device side of the protection resistor to avoid damage to the R2 driver.
R3	A logic 1 on the RD3 signal turns the R3 driver on and routes current from the R3 pin to the RYE pin. In the option where the RYE pin is connected to ground, the R3 pin can sink current from a relay connected to VCCD. Another option is to connect the RYE pin to the B (Ring) lead and connect a test load between R3 and the A (Tip) lead. This technique avoids the use of a relay to connect a test load. However, it does not isolate the subscriber line from the line card. The test load must be connected to the Le79231 ISLIC device side of the protection resistor to avoid damage to the R3 driver.

Control bits RD1, RD2, and RD3 do not affect the operating mode of the Le79231 ISLIC device. These signals usually perform the following functions.

Thermal-Management Equations

Applies to all modes except Standby, which has no thermal management..

Equation	Description
$I_L < 5$ mA $P_{SLIC} = (S_{BAT} – I_L(R_L + 2R_{FUSE})) • I_L + 0.3$ W $PT_{RTMG} = 0$	TMG resistor-current is limited to be 5 mA < I_L. If $I_L < 5$ mA, no current flows in the TMG resistor and it all flows in the Le79231 ISLIC device.
$I_L > 5$ mA $RMGPi = RMGLi = R_{TMG}$ PT_{RTMG}: total power dissipation of RMGPi and RMGLi $R_{TMG} = (S_{BAT} – I_L(R_L + 2R_{FUSE})) / (2(I_L – 5\text{ mA}))$ $P_{SLIC} = I_L(S_{BAT} – I_L(R_L + 2R_{FUSE})) + 0.3\text{ W} – PT_{RTMG}$ $PT_{RTMG} = (I_L – 5\text{ mA})^2(2R_{TMG})$	These equations are valid when $R_{TMG} • (I_L – 5\text{ mA}) < (S_{BAT} – (R_L + R_F)I_L) / 2 – 2$ because the longitudinal voltage is one-half the battery voltage and the TMG switches require approximately 2 V. To choose a power rating for R_{TMG}: $P_{RATING} > PT_{RTMG} / 2$

TIMING SPECIFICATIONS

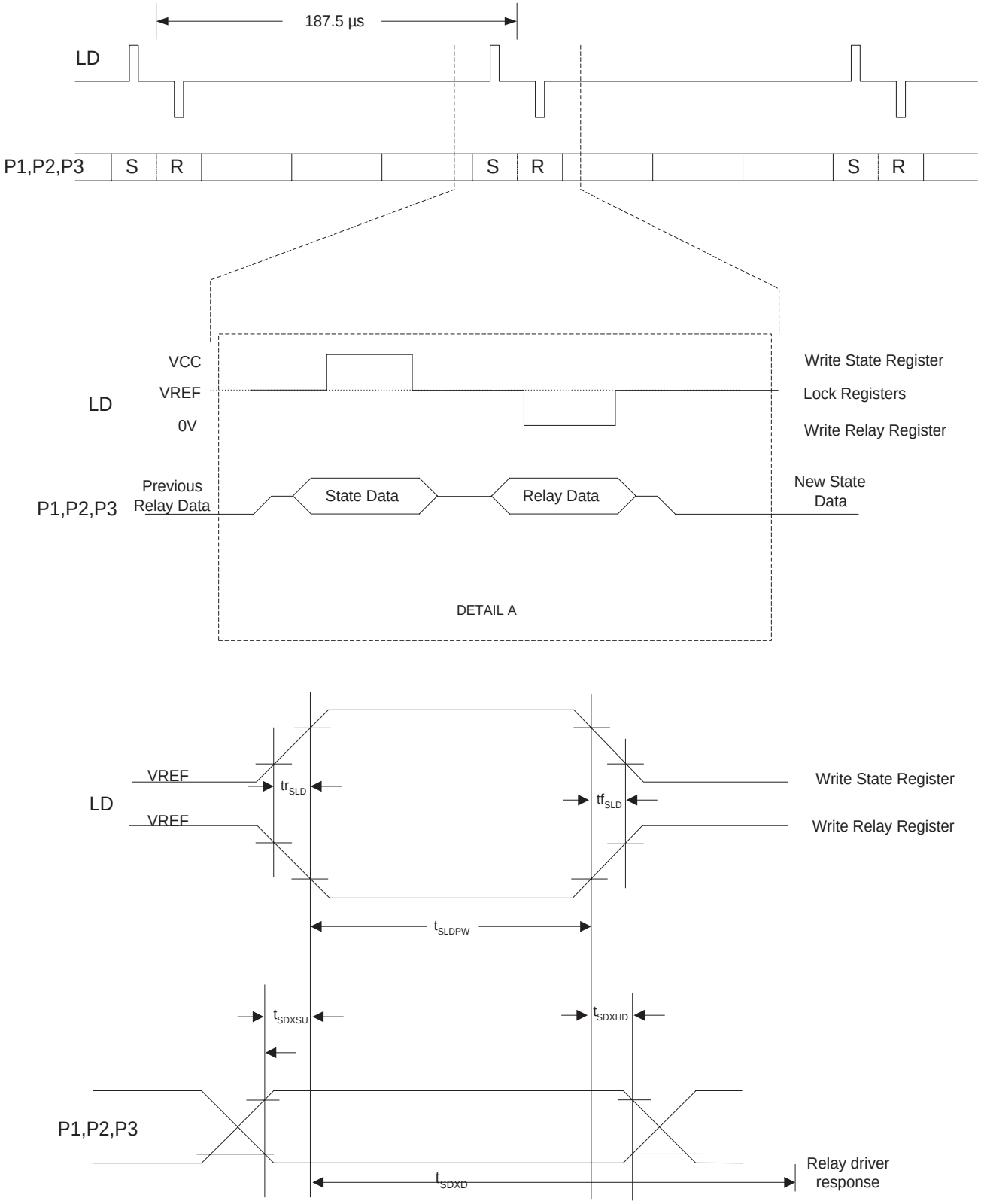
Symbol	Signal	Parameter	Min	Typ	Max	Unit
trSLD	LD	Rise time Le79231 ISLIC device LD pin			2	µs
tfSLD	LD	Fall time Le79231 ISLIC device LD pin			2	
tSLDPW	LD	LD minimum pulse width	3			
tSDXSU	P1,P2,P3	P1–3 data Setup time	4.5			
tSDXHD	P1,P2,P3	P1–3 data hold time	4.5			
tSDXD	P1,P2,P3	Max P1–3 data delay			5	

Note:

1. *The P1–3 pins are updated continuously during operation by the LD signal.*
2. *After a power-on reset or hardware reset, the relay outputs from the Le79231 ISLIC device turn all relays off. An unassuming state is to place the relay control pins, which are level triggered, to a reset state for all relays. Any noise encountered only raises the levels toward the register lock state.*
3. *When writing to the Le79231 ISLIC device registers, the sequence is:*
   a) *Set LD pin to mid-state*
   b) *Place appropriate data on the P1–3 pins*
   c) *Assert the LD pin to High or Low to write the proper data*
   d) *Return LD pin to mid-state*

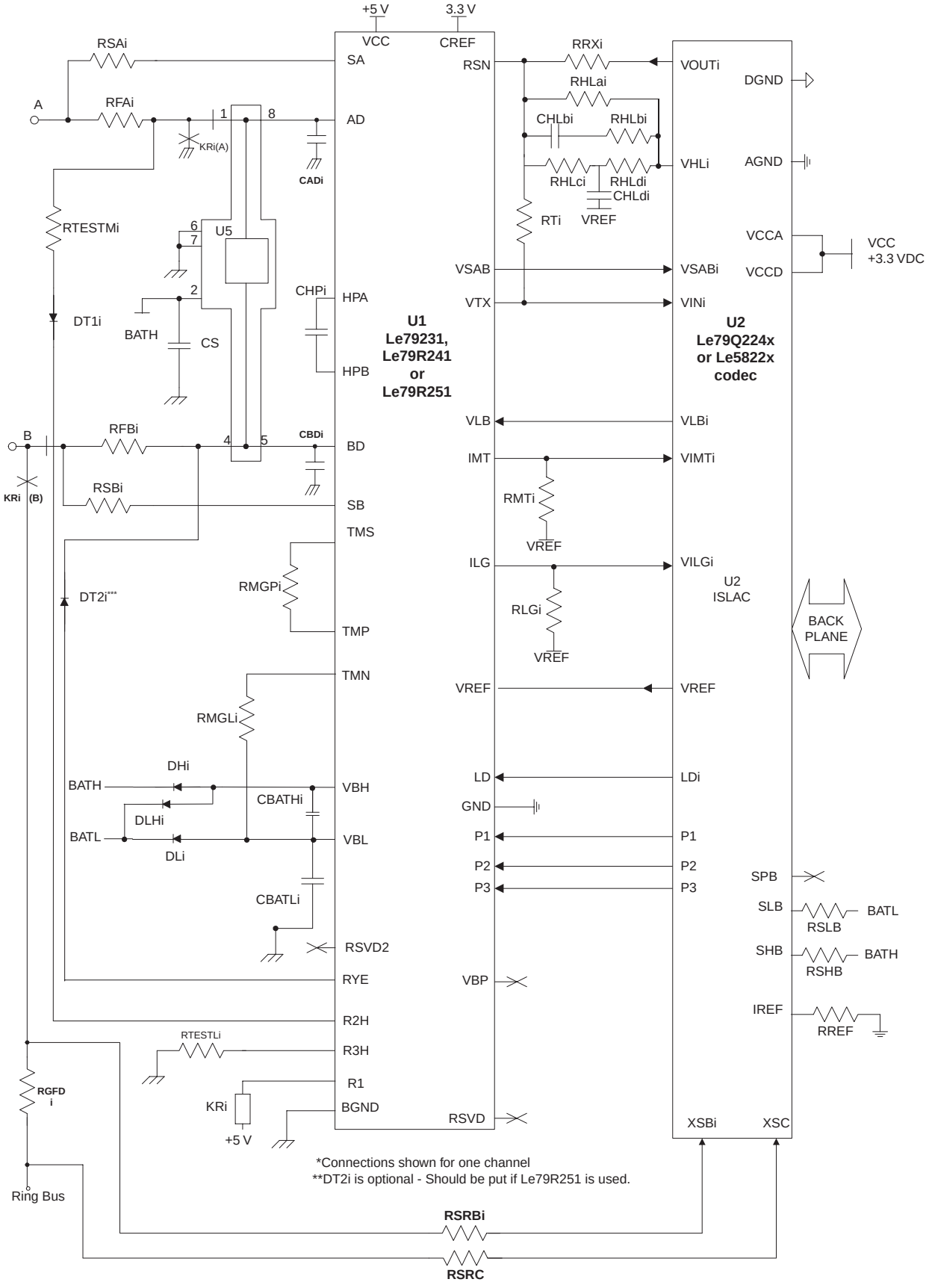
4. *Le79231 ISLIC device registers are refreshed at 5.33 kHz when used with a Le79Q224x or Le79228 codec.*
5. *If the clock or MPI becomes disabled, the LD pins and P1–3 returns to 0 V state, thus protecting the Le79231 ISLIC device and the line connection.*
6. *Not tested in production. Guaranteed by characterization.*

WAVEFORMS



APPLICATION CIRCUIT

External Ringing Line card Schematic



*Connections shown for one channel
**DT2i is optional - Should be put if Le79R251 is used.

LINE CARD PARTS LIST

The following list defines the parts and part values required to meet target specification limits for channel i of the line card (i = 1, 2, 3, 4).

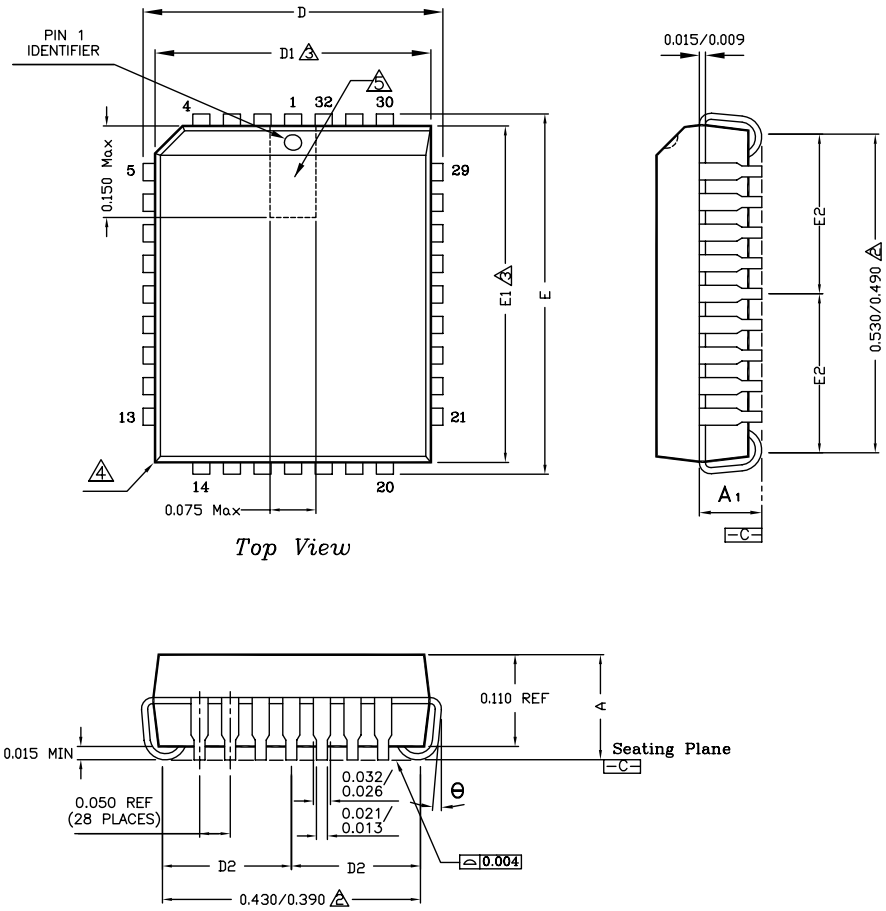
Item	Type	Value	Tol.	Rating	Comments
U1	Le79R231 ISLIC device				
U2	VE790 series ISLAC device				codec
U5	TISP61089			80 V	Transient Voltage Suppressor, Power Innovations
DLH_i[1], DH_i, DL_i, $DT1_i$ $DT2i$[2]	Diode	100 mA		100 V	50 ns response time
RFA_i, RFB_i	Resistor	50 Ω	2%	2 W	Fusible or PTC protection resistors
RSA_i, RSB_i	Resistor	200 kΩ	2%	1/4 W	Sense resistors
RT_i	Resistor	80.6 kΩ	1%	1/8 W	Impedance control resistor
RRX_i	Resistor	90.9 kΩ	1%	1/8 W	Receive path gain resistor
RREF	Resistor	69.8 kΩ	1%	1/8 W	Current reference setting resistor
$RMGL_i$, $RMGP_i$	Resistor	1 kΩ	5%	1 W	Thermal management resistors
RSHB, RSLB	Resistor	750 kΩ	1%	1/8 W	Battery Sense Resistors
$RHLa_i$	Resistor	40.2 kΩ	1%	1/10 W	Feed/Metering resistor
$RHLb_i$	Resistor	4.32 kΩ	1%	1/10 W	Feed/Metering resistor
$RHLc_i$	Resistor	2.87 kΩ	1%	1/10 W	Feed/Metering resistor
$RHLd_i$	Resistor	2.87 kΩ	1%	1/10 W	Feed/Metering resistor
$CHLb_i$	Capacitor	3.3 nF	10%	10 V	Feed/Metering capacitor - Not Polarized
$CHLd_i$	Capacitor	0.82 mF	10%	10 V	Feed/Metering capacitor - Ceramic
RMT_i	Resistor	3.01 kΩ	1%	1/8 W	Metallic Current Sense Resistors
RLG_i	Resistor	6.04 kΩ	1%	1/8 W	Longitudinal Current Sense Resistors
$RTESTM_i$	Resistor	2 kΩ	1%	1 W	Metallic test
$RTESTL_i$	Resistor	2 kΩ	1%	1 W	Longitudinal test
CAD_i, CBD_i [3]	Capacitor	22 nF	10%	100 V	Ceramic
$CBATH_i$, $CBATL_i$	Capacitor	100 nF	20%	100 V	Ceramic
CHP_i	Capacitor	22 nF	20%	100 V	Ceramic
CS_i[3]	Capacitor	100 nF	20%	100 V	Protector speed up capacitor
$RGFD_i$	Resistor	510 Ω	2%	2 W	1.2 W typ
$RSRB_i$, RSRC	Resistor	750 kΩ	1%	1/4 W	External Ringing sense resistors
KR_i	Relay	5 V Coil			DPDT

Notes:

1. *Required to insure VBH < VBL during startup. May not be needed for some supplies.*
2. *DT2i is optional - Should be put if Le79R251 is used.*
3. *Value can be adjusted to suit application.*

PHYSICAL DIMENSIONS

32-Pin PLCC



32-Pin PLCC			
JEDEC # MS-016			
Symbol	**Min**	**Nom**	**Max**
A	0.125	--	0.140
A1	0.075	0.090	0.095
D	0.485	0.490	0.495
D1	0.447	0.450	0.453
D2	0.205 REF		
E	0.585	0.590	0.595
E1	0.547	0.550	0.553
E2	0.255 REF		
θ	0 deg	--	10 deg

NOTES:

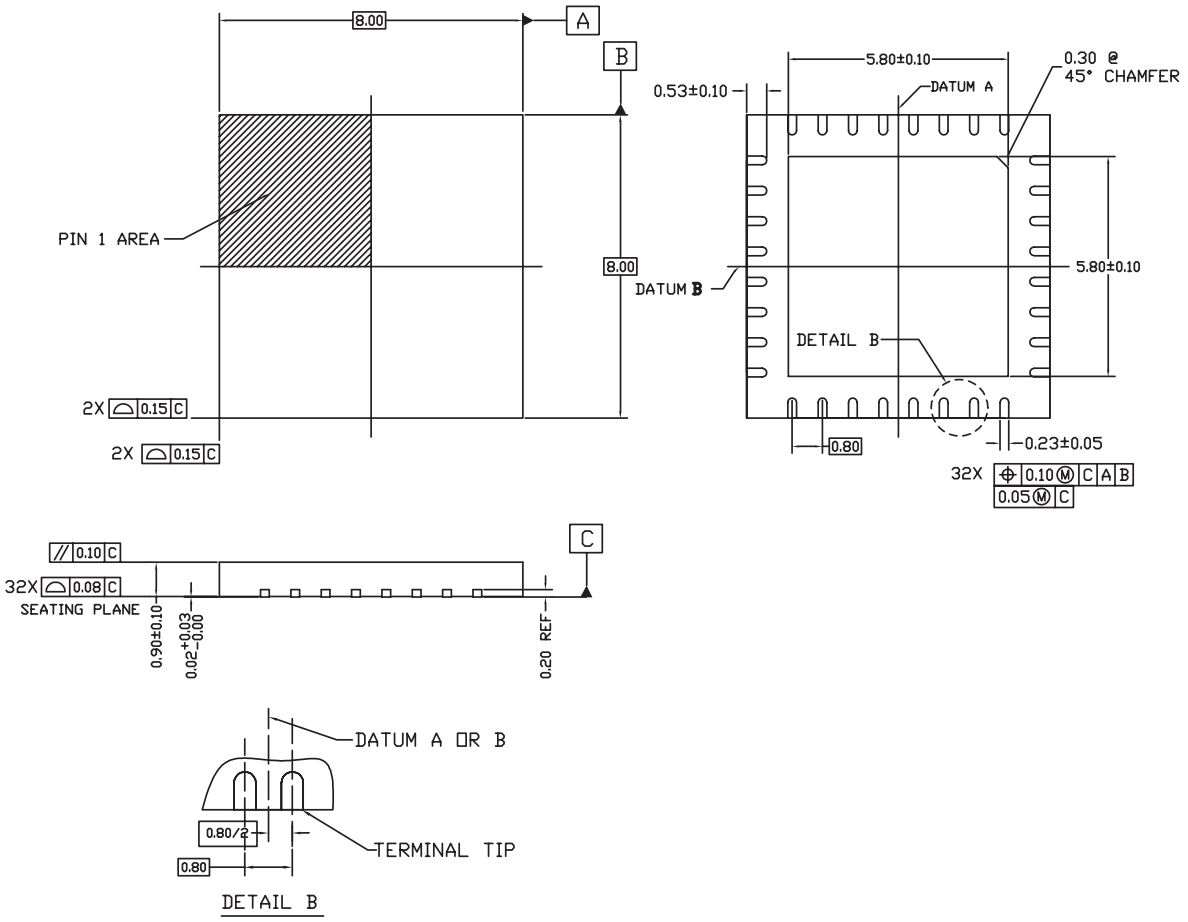
1. Dimensioning and tolerancing conform to ASME Y14,5M-1994.
2. To be measured at seating plan - C - contact point.
3. Dimensions “D1” and “E1” do not include mold protrusion. Allowable mold protrusion is 0.010 inch per side. Dimensions “D” and “E” include mold mismatch and determined at the parting line; that is “D1” and “E1” are measured at the extreme material condition at the upper or lower parting line.
4. Exact shape of this feature is optional.
5. Details of pin 1 identifier are optional but must be located within the zone indicated.
6. Sum of DAM bar protrusions to be 0.007 max per lead.
7. Controlling dimension : Inch.
8. Reference document : JEDEC MS-016

32-Pin PLCC

Note:

Packages may have mold tooling markings on the surface. These markings have no impact on the form, fit or function of the device. Markings will vary with the mold tool used in manufacturing.

32-Pin QFN



Symbol	32 LEAD QFN		
	Min	Nom	Max
A	0.80	0.90	1.00
A2		0.57 REF	
b	0.18	0.23	0.28
D		8.00 BSC	
D2	5.70	5.80	5.90
E		8.00 BSC	
E2	5.70	5.80	5.90
e		0.80 BSC	
L	0.43	0.53	0.63
N		32	
A1	0.00	0.02	0.05
A3		0.20 REF	
aaa		0.20	
bbb		0.10	
ccc		0.10	

NOTES:
1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters. ⌖ is in degrees.
3. N is the total number of terminals.
4. The Terminal #1 identifier and terminal numbering convention shall conform to JEP 95-1 and SSP-012. Details of the Terminal #1 identifier are optional, but must be located within the zone indicated. The Terminal #1 identifier may be either a mold or marked feature.
5. Coplanarity applies to the exposed pad as well as the terminals.
6. Reference Document: JEDEC MO-220.
7. Lead width deviates from the JEDEC MO-220 standard.

32-Pin QFN

Note:

Packages may have mold tooling markings on the surface. These markings have no impact on the form, fit or function of the device. Markings will vary with the mold tool used in manufacturing.

REVISION HISTORY

Revision A to Revision B

- Revision A was a condensed version of the data sheet. Revision B contains the full version.

Revision B to Revision C

- Page 12, Linecard Parts List, Rows CHLbi and CHLdi: switched the numbers in the “Values” column.

Revision C to Revision D

- Applied new format.
- Global change: RTMG1 to RMGLi, and RTMG2 to RMGPi.
- Updated Device Internal Block Diagram.
- Updated pin description for LD pin.
- Modified text in "Electrical Operating Ranges" section.
- Modified text in "Environmental Operating Ranges" section.
- “Absolute Maximum Rating” for humidity changed from “tbd” to 5% - 95%.
- Under "Specifications", Power Dissipation table, changed the Power Supply Current On-Hook Disconnect value from 0.5 to 0.4.
- Made changes throughout the DC Specifications table.
- Updated “Target Specifications” for rows 10, 12, and 19.
- Updated “Transmission Specifications” for rows 5, 6, 7, 8, 10, 12 and 13.
- Renamed "Fault Indications" table to "Thermal Shutdown Fault Indications"; modified text.
- Modified text in "Operating Modes" section.
- Modified Thermal Management Equations for $I_L > 5$ mA
- Updated Waveforms graphic.
- Updated External Ringing Linecard Schematic.

Revision D to Revision E

- Added QFN package data to “Connection Diagram,” “Absolute Maximum Ratings,” and “Physical Dimensions.”
- Updated "Am" OPNs (Ordering Part Numbers) to "Le" throughout document
- The following changes were made to the "Ordering Information" section:
  - Removed chip graphic
  - Added entries for Le79231JC and Le79231QC
  - Added notes
- In "Features," added bullet for space savings feature
- Removed references to DISLAC documents in "Related Literature"
- Standardized notes in "Absolute Maximum Ratings" section
- In "Thermal Management Equations", IL > 5 mA, deleted the last sentence in the Description section
- Updated 32-Pin PLCC physical dimensions graphic
- In "Electrical Characteristics", Absolute Maximum Ratings table, added Theta JA data for both packages

Revision E to F1

- Added green package OPN to *Ordering Information*, on page 1
- Added *Package Assembly*, on page 10
- Modified external ringing schematic and BOM (removed CSS capacitor)
- Updated QFN *Physical Dimensions* drawing

Revision F1 to F2

- Enhanced format of package drawings in *Physical Dimensions*, on page 21
- Added new headers/footers due to Zarlink purchase of Legerity on August 3, 2007

For more information about all Zarlink products visit our Web Site at:

www.zarlink.com